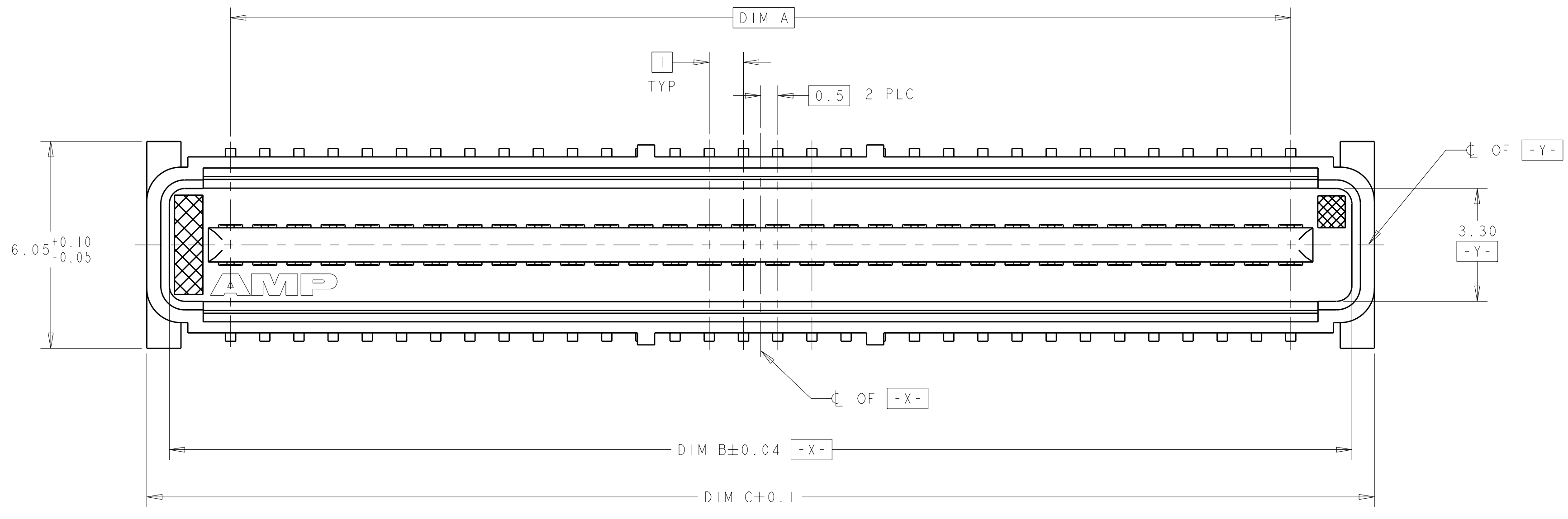
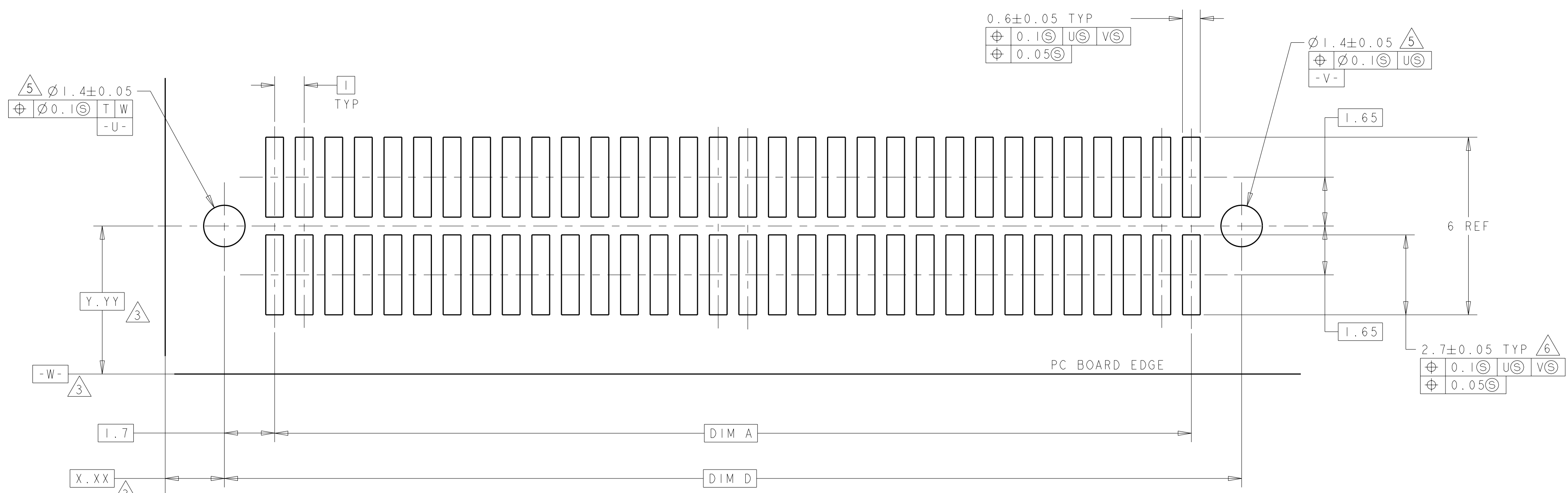
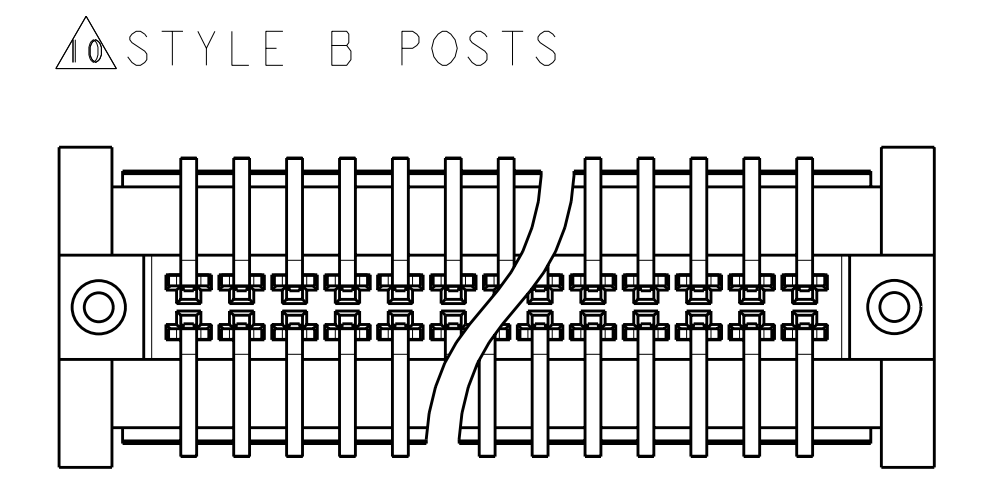
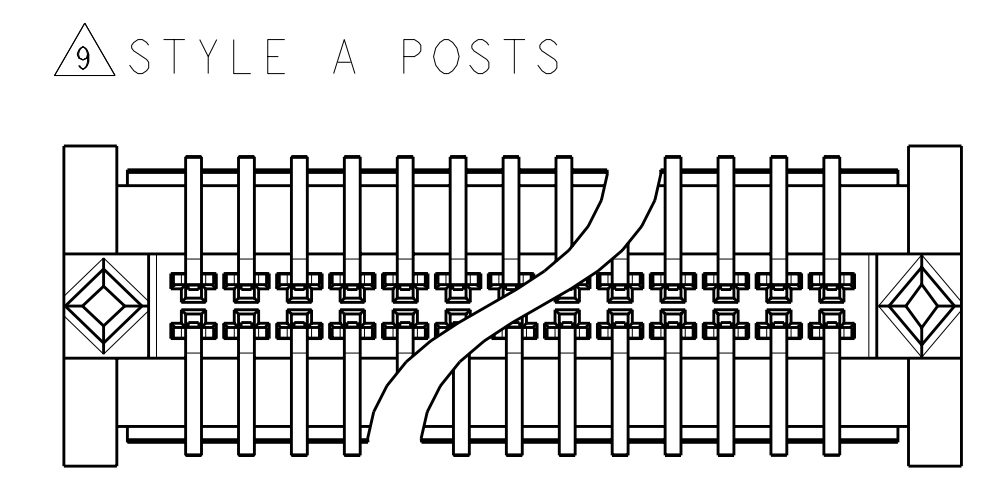
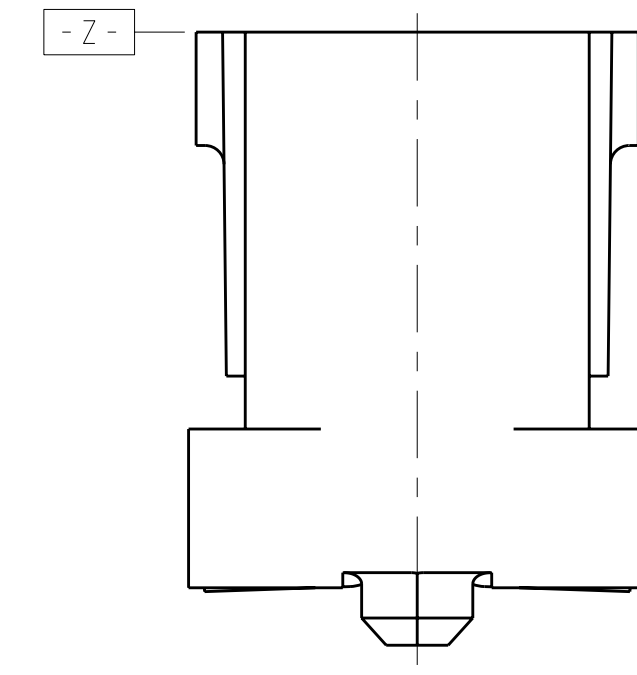
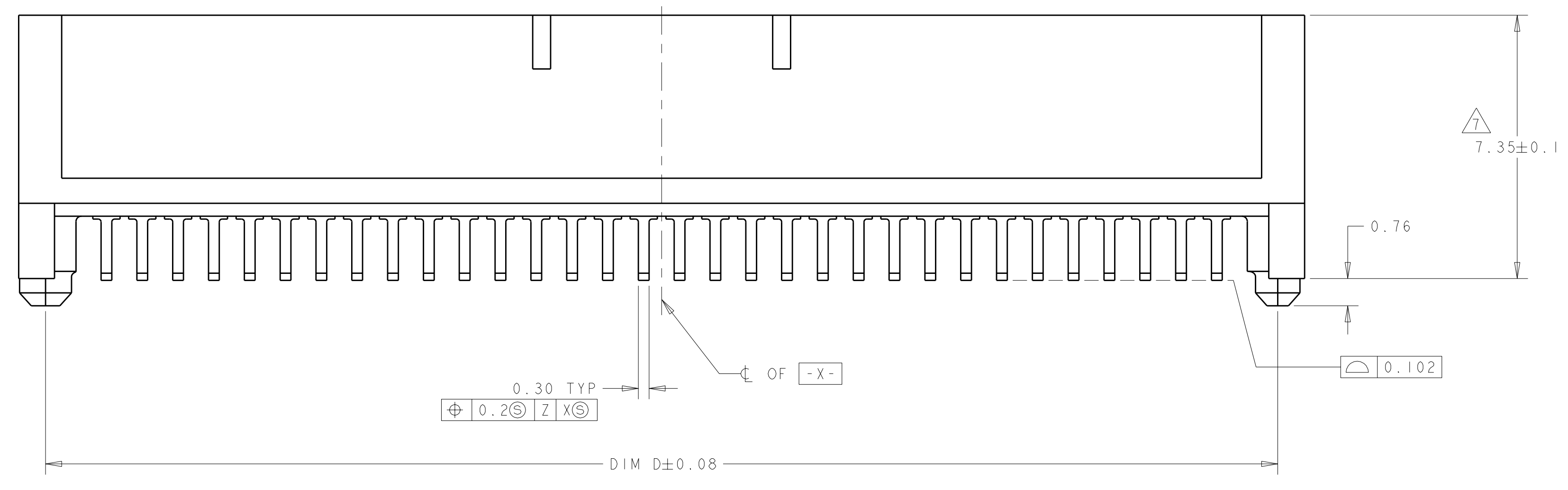


LOC	DIST	REV	DATE	BY	CHK	APP'D
AD	00	0	30SEP2004	BC	RW	
		A	16SEP2005	BC	RW	
		B	10JUL2008	DH	DB	
		B1	12SEP2009	AEG	HM	



1. HOUSING MATERIAL: LIQUID CRYSTAL POLYMER. COLOR: BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAAB, SOLDER TAILS PLATED TIN.
3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
4. PACKAGED IN TAPE ON REEL PER EIA-481.
5. 1.5 MIN DIAMETER HOLE SHOULD BE USED IF USING POST STYLE "A" AND PLACING ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAAB, HOWEVER 2.7 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
7. REFERRED TO AS DIM N IN EIA 700AAAAB SPECIFICATION.
8. CONTACT FINISH: 0.00381 MINIMUM MATTE TIN PER ASTM B 545 ON SOLDER AREA, 0.00127 MINIMUM GOLD PER ASTM B 488 ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL PER SAE-AMS-QQ-N-290 ON ENTIRE CONTACT.
9. SQUARE AND DIAMOND SHAPED POSTS
10. ROUND SHAPED POSTS



RECOMMENDED PC BOARD LAYOUT

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HGTS	POS	PART NO
10	8	44.4	45.9	44.58	41	9, 11, 14	84	3-5120526-2
10	8	34.4	35.9	34.58	31	9, 11, 14	64	3-5120526-1
10	2	44.4	45.9	44.58	41	9, 11, 14	84	2-5120526-2
10	2	34.4	35.9	34.58	31	9, 11, 14	64	2-5120526-1
9	8	44.4	45.9	44.58	41	9, 11, 14	84	1-5120526-2
9	8	34.4	35.9	34.58	31	9, 11, 14	64	1-5120526-1
9	2	44.4	45.9	44.58	41	9, 11, 14	84	5120526-2
9	2	34.4	35.9	34.58	31	9, 11, 14	64	5120526-1

**TYCO ELECTRONICS CORPORATION**  
 Harrisburg, PA 17105-3608

**AMP 4805 REV 31MAR2000**

**PLUG ASSY, 1.0mm FH(IEEE1386) CONNECTOR**

30SEP04  
 B. CARBO  
 R. WERTZ  
 R. WERTZ

502-1079  
 114-25045

00779  
 5120526

SCALE 10:1